

## Chemask® Solder Masking Agent

**Product# CM8, CM1**

### Product Description

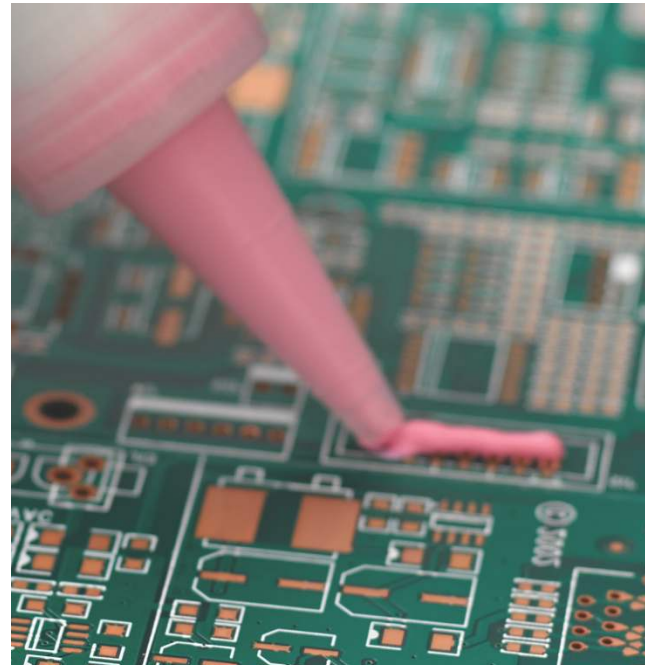
Chemask Peelable is a fast curing peelable solder masking agent. It contains a high temperature resistant compound that protects component-free areas during wave soldering. Chemask may be used to protect pins, posts, contacts and edge connections during conformal coating processes.

- Stable to 515°F (268°C)
- Compatible with rosin, water soluble fluxes and cleaning solvents
- Leaves no residue
- Dries tack free in 30 minutes
- Non-contaminating

### Typical Applications

Chemask protects:

- Component free areas for soldering
- Components
- Pin connectors during soldering
- Temperature sensitive components during wave soldering
- Sockets
- Board areas from conformal coating



### Typical Product Data and Physical Properties

<b>Base Material</b>	Natural latex rubber
<b>Color</b>	Pink
<b>Solvent Stability</b> (cured mask)	Stable in all hydrocarbons, hydrofluorocarbons, water and chlorinated solvents
<b>Flux Compatibility</b>	All types
<b>Temperature Stability</b>	515°F/ 268°C
<b>Tack-Free Drying Time</b> (10 mils @ 77°F/25°C)	15 min.
<b>Cure Time</b> (10 mils @ 77°F/25°C)	30 min.
<b>Viscosity (@ 77°F)</b> (± 500 cps)	20,000-28,000 cps
<b>Viscosity Adjusted With</b>	DI water
<b>Solids Content</b>	~ 60%
<b>Flash Point</b>	Nonflammable
<b>Weight/Gallon</b>	7.2 lbs.
<b>Shelflife</b>	2 years
<b>RoHS Compliant</b>	Yes

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### Compatibility

Chemask is generally compatible with most materials used in printed circuit board fabrication. As with any solder masking agent, compatibility with substrate must be determined on a non-critical area prior to use.

### Application Method

Squeeze Bottle/Syringe	Yes
Spatula	Yes
Screening	No
Automatic Dispensing	Yes
Removal/Clean-up	By Hand

### Usage Instructions

**For industrial use only. Read SDS carefully prior to use.**

Chemask solder masking agent is engineered for all electronic manufacturing applications. When applying by hand using squeeze bottle or spatula, insure that all areas of the pretinned hole are evenly covered on the side to be soldered. Automatic dispensing equipment may also be used as appropriate.

**REMOVAL:** After allowing the mask to become fully cured, peelable solder mask can be removed by hand or by the use of tweezers. Depending on ambient conditions, peelable mask may remain on assemblies for extended periods of time prior to component insertion.

### Availability

<b>CM8</b>	8 fl. oz. / 236 mL Liquid Squeeze Bottle
<b>CM1</b>	1 gal. / 3.7 L Liquid

### Environmental Impact Data

CFC	0.0%
HCFC	0.0%
CL Solv.	0.0%
VOC	3.1%
HFC	0.0%
ODP	0.00

CFC, HCFC, CL. SOLV., VOC, and HFC numbers shown are the content by weight. Ozone depletion potential (ODP) is determined in accordance with the Montreal Protocol and U.S. Clean Air Act of 1990. The ODP of this product is 0.0. It is the sum of the ODP of the substances that may contribute to the depletion of stratospheric ozone, based upon the weight of each substance in the product's formulation.

### Technical and Application Assistance

Chemtronics provides a technical hotline to answer your technical and application related questions.

*The toll free number is: 1-800-TECH-401.*

### Note:

This information is believed to be accurate. It is intended for professional end users having the skills to evaluate and use the data properly. CHEMTRONICS does not guarantee the accuracy of the data and assumes no liability in connection with damages incurred while using it.